

PIN	DIM.A	DIM.B	DIM.C
02	1.25	6.45	7.45
03	2.50	7.70	8.70
04	3.75	8.95	9.95
05	5.00	10.20	11.20
06	6.25	11.45	12.45
07	7.50	12.70	13.70
08	8.75	13.95	14.95
09	10.00	15.20	16.20
10	11.25	16.45	17.45
15	17.50	17.70	23.70

REV	MODIFICATION	DATE	DRAW
A3	Release To ECN20110611	2011.06.15	Ivy
A4	Release To ECN20130306	2013.03.14	Seven
A5	Release To ECN20160401	20160415	Michelle

**RoHS Compliant**

Specification  
 1.Current Rating:1A AC  
 2.Voltage Rating:100V AC  
 3.Contact Resistance:30mΩ Max.  
 4.Insulation Resistance:500MΩ Min. At DC100V  
 5.Dielectric Withstanding Voltage:AC500V/Minute  
 6.Operating Temperature:-35°C~+85°C

Material:  
 1.Housing:High Temperature Thermoplastic UL94V-0  
 2.Tab:Copper Alloy t=0.40mm  
 3.Contact Pin:Copper Alloy t=0.30mm

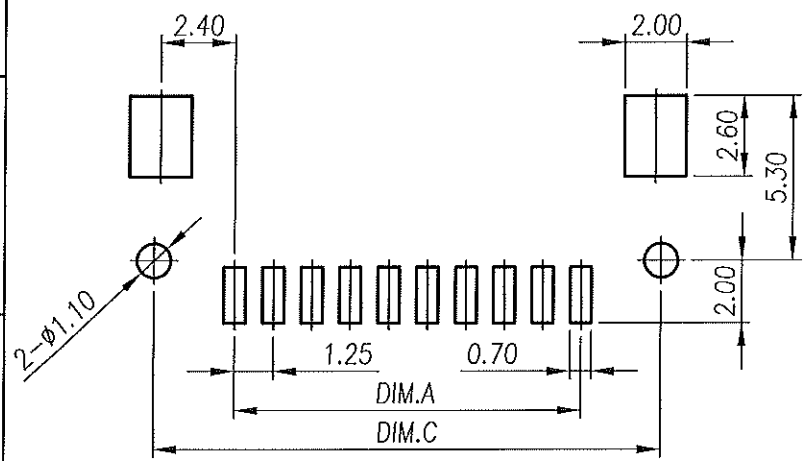
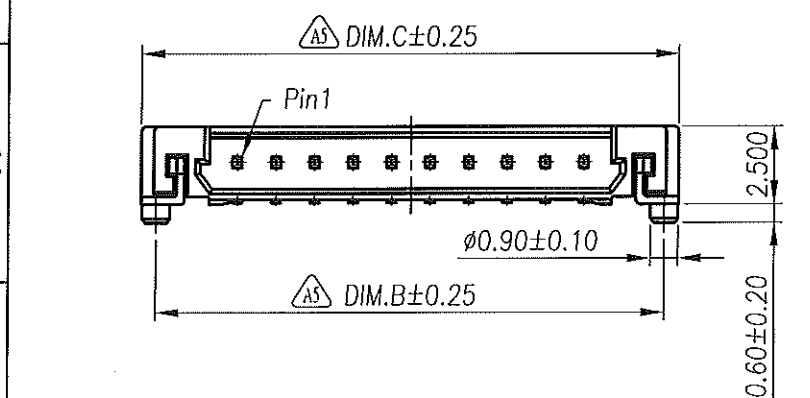
Finish:  
 1.Housing:See P/N Option  
 2.Tab:Tin Plated Over Nickel  
 3.Contact Pin:See P/N Option  
 Part No.:AS07803 XX X X X 1

No. Of Pin  
02~10,15

Packing  
1:T&R  
4:Tube

Housing Material  
 5:HTN UL94V-0 Natural Non-HF  
 K:HTN UL94V-0 Natural H.F  
 W:HTN UL94V-0 Black H.F

Plating  
 1:Bright Tin Plated Over Ni.  
 2:Matte Tin Plated Over Ni.  
 3:Gold Plated Over Ni.

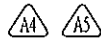


RECOMMENDED P.C.B LAYOUT

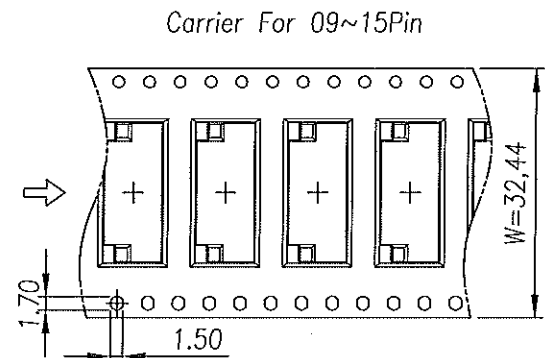
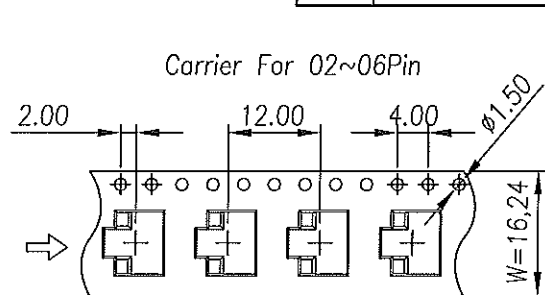
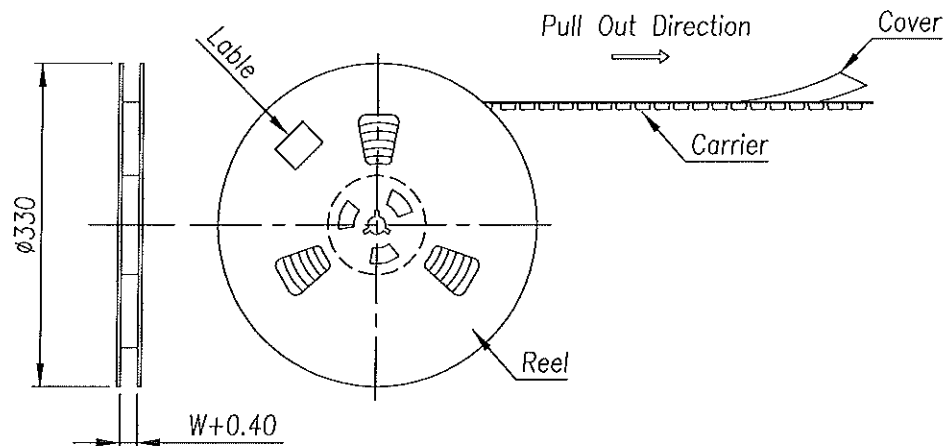
**金上達科技股份有限公司**  
**GOLDENSUNDA TECHNOLOGY CO.,LTD**

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 1.25mm 90° SMT With Post For 02~10,15Pin	
.x± 0.35	.x'± 2'	APR. Jefferson 20160418	PART NO. AS07803XXXXX1	DWG NO. AS07803XXXXX1
.xx± 0.25	.x'± 1'	CHK. Abel 20160418	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20160418	SIZE: A4	SCALE 4:1
			SHEET 1 / 2	REV A5

**RoHS Compliant**

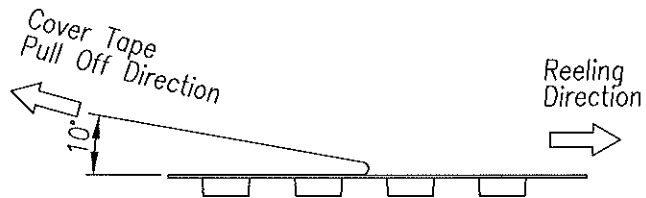
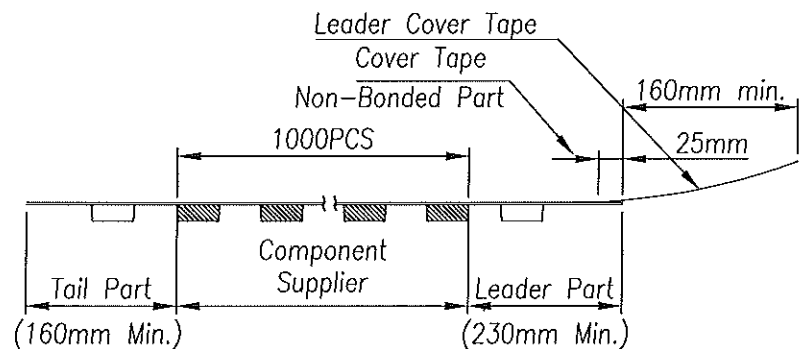
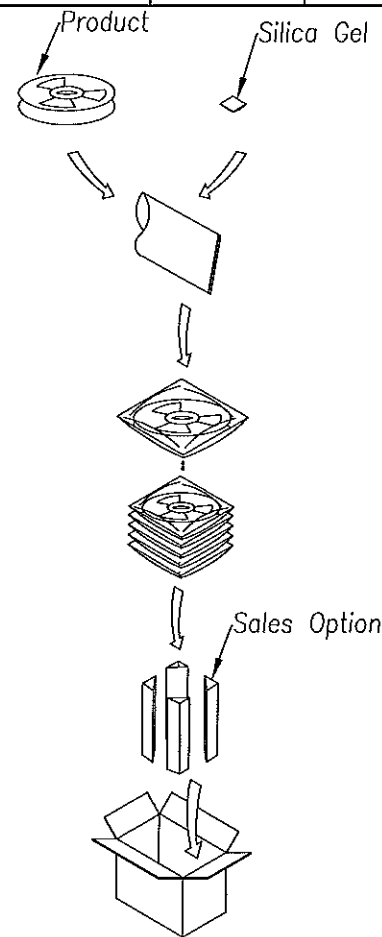


REV	MODIFICATION	DATE	DRAW
A3	Release To ECN20110611	2011.06.15	Ivy
A4	Release To ECN20130306	2013.03.14	Seven
A5	Release To ECN20160401	20160418	Michelle



Notes:

1. Material : PS
2. Part No.: AS07803XXXX11



PIN NO.	W±0.30	PCS/REEL
02	16	1000
03~06	24	
09~10	32	
15	44	



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.x± 0.35	.x:± 2'	APR. Jefferson 20160418	PART NO. AS07803XXXXX1	DWG NO. AS07803XXXXX1
.xx± 0.25	.x:± 1'	CHK. Abel 20160418	UNITS: mm CUSTOMER DRAWING	
.xxx± 0.15	.xx:± 0.5'	DRA. Michelle 20160418	SIZE: <b>A4</b>	SCALE Free SHEET 2 / 2 REV A5